

Ultra Low Power Sensor Controller TI BoosterPack™

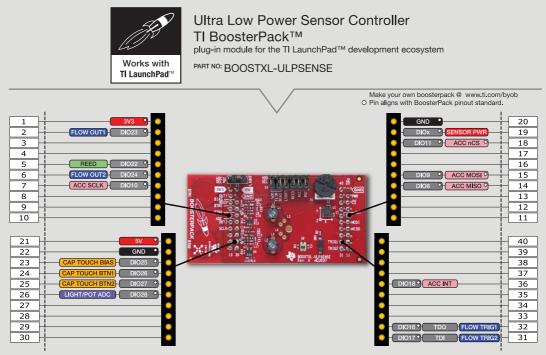
plug-in module for the TI LaunchPad™ Development ecosystem

PART NO: BOOSTXL-ULPSENSE



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